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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/295,431	04/20/1999	TETSUZO YOSHIMURA	6136/53461	7173

30764 7590 05/18/2004

SHEPPARD, MULLIN, RICHTER & HAMPTON LLP
333 SOUTH HOPE STREET
48TH FLOOR
LOS ANGELES, CA 90071-1448

EXAMINER	
MOONEY, MICHAEL P	
ART UNIT	**PAPER NUMBER**
2877	

DATE MAILED: 05/18/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

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APPLICATION NO./ CONTROL NO.	FILING DATE	FIRST NAMED INVENTOR / PATENT IN REEXAMINATION	ATTORNEY DOCKET NO.
09295431	4/20/99	Yoshimura	6136/53461

EXAMINER
Michael Mooney

ART UNIT	PAPER
2877	00

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Commissioner for Patents

The enclosed contains changes resulting from a printer query..

CHANGES RESULTING FROM A PRINTER QUERY

(1) ***Please enter this abstract (Approved by Atty. Yeager, Reg. No. 35,419):***

ABSTRACT OF THE DISCLOSURE

Opto-electrical systems having electrical and optical interconnections formed in thin layers are disclosed. In one set of preferred embodiments, optical signals are conveyed between layers by respective vertical optical couplers disposed on the layers. In other preferred embodiments, optical signals are conveyed by stack optical waveguide coupling means. Yet other preferred embodiments have electrical via means formed in one or more layers to covey electrical signals between two or more layers.

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(2) *On page 58, lines 10-14, please change the sentence (Approved by Atty. Yeager, Reg. No. 35,419):*

> "(For diffusion bonding of two metal pads together in a Z-connection, the method newly invented by Messrs. Kuo-Chuan Liu and Michael G. Lee and described in yet to be filed patent application serial No. _____, entitled *"Transient Liquid Alloy Bonding,"* (TBL) and assigned to the assignee of the present application, appears to be useful in the structures of the present application.)"

to read as:

> (For diffusion bonding of two metal pads together in a Z-connection, the method newly invented by Messrs. Kuo-Chuan Liu and Michael G. Lee and described filed patent application Ser. No. 10/066,485, entitled "Method for Joining Conductive Structures and an Electrical Conductive Article" and assigned to the assignee of the present application, U.S. Publication No. 2003-0019568-A1, appears to be useful in the structures of the present application.)

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Michael P. Mooney whose telephone number is 571-272-2422. The examiner can normally be reached during weekdays, M-F.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Frank G. Font can be reached on 571-272-2415. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 571-272-1562.

Michael P. Mooney
Examiner
Art Unit 2877

Frank G. Font
Supervisory Patent Examiner
Art Unit 2877

FGF/mpm
5/5/04